

	TECH	INICAL DATA SH	IEET	2/5	
STRAIGHT FEMALE RECEPTACLE FOR PCB				R209.408.052	
SMT	TYPE - RE	Series : MMS			
			1		
<b>PACKAGING</b>			<b>SPECIFICATION</b>		
Standard	Unit	Other			
500	-	Contact us			
ELECTRICAL CHARACTERISTICS			ENVIRONMENTAL		
Impedance Frequency VSWR Insertion loss RF leakage Voltage rating	0-6 * + 0,0000 ** - ( NA	Ω GHz x F(GHz) Maxi √F(GHz) dB Maxi - F(GHz)) dB mini Veff Maxi	Operating temperature Hermetic seal-40/+125 ° CNANAPanel leakageNA		
Dielectric withstanding volta Insulation resistance		Veff mini MΩ mini	OTHERS CHARACTERISTICS		
			Assembly instru	uction	
MECHANICAL	CHARACTE	RISTICS	Others : *1.2 à 2GHz/Avg	s 1,07 **Max 0.07/Avg 0.06	
Center contact retention					
Axial force – Mating end		N mini			
Axial force – Opposite end Torque		N mini N.cm mini			
Recommended torque					
Mating		N.cm			
Panel nut	NA	N.cm			
Mating life Weight	50 0,1000	Cycles mini g			
<b>Issue :</b> 0743 A				aunsauns	
In the effort to improve our pronecessary.	oducts, we reserve	the right to make ch	anges judged to be	RADIALL	

#### TECHNICAL DATA SHEET

## STRAIGHT FEMALE RECEPTACLE FOR PCB

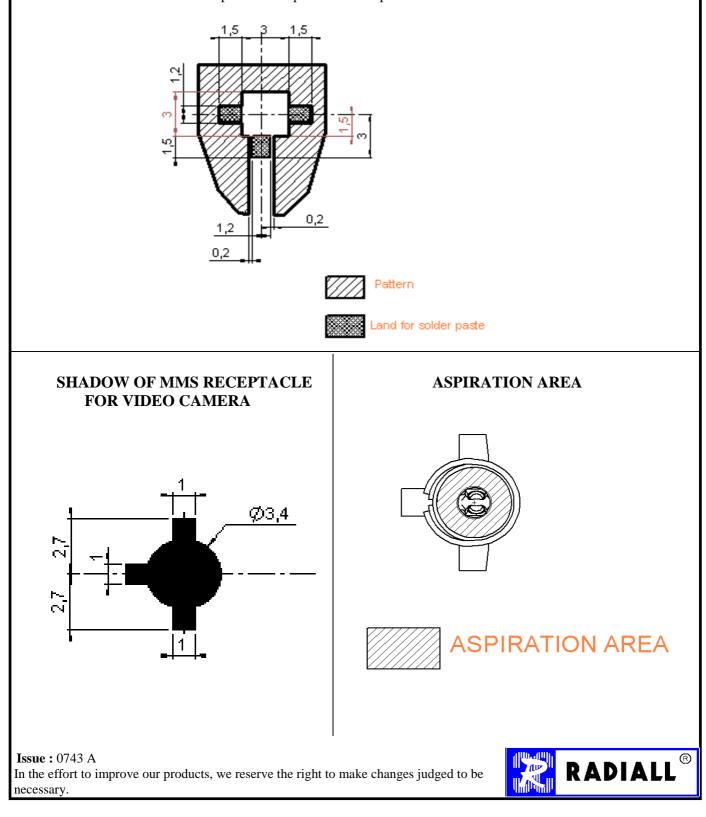
#### **SMT TYPE - REEL OF 500**

R209.408.052

Series : MMS

#### **MMS SERIES – INFORMATION**

Coplanar line : Ground and signal are on the same side . Thicknass of PCB : 1mm The material of PCB is glass-epoxy composite. (Er = 4.8) The sold er resist should be printed except for the land pattern on the PCB.



#### TECHNICAL DATA SHEET

## STRAIGHT FEMALE RECEPTACLE FOR PCB

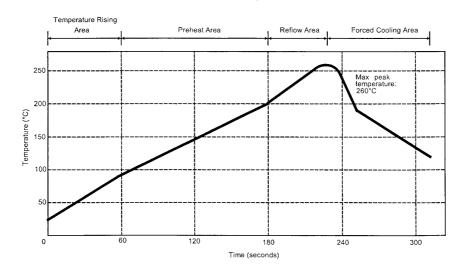
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# SOLDER PROCEDURE

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.



<b>TEMPERATURE PROFILE</b>

Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec



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